

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (U-MOSIII)

TPCS8212

Lithium Ion Battery Applications

- Small footprint due to small and thin package
- Low drain-source ON resistance: $R_{DS(ON)} = 16 \text{ m}\Omega$ (typ.)
- High forward transfer admittance: $|Y_{fs}| = 11 \text{ S}$ (typ.)
- Low leakage current: $I_{DSS} = 10 \mu\text{A}$ (max) ($V_{DS} = 20 \text{ V}$)
- Enhancement mode: $V_{th} = 0.5 \sim 1.2 \text{ V}$ ($V_{DS} = 10 \text{ V}$, $I_D = 200 \mu\text{A}$)
- Common drain

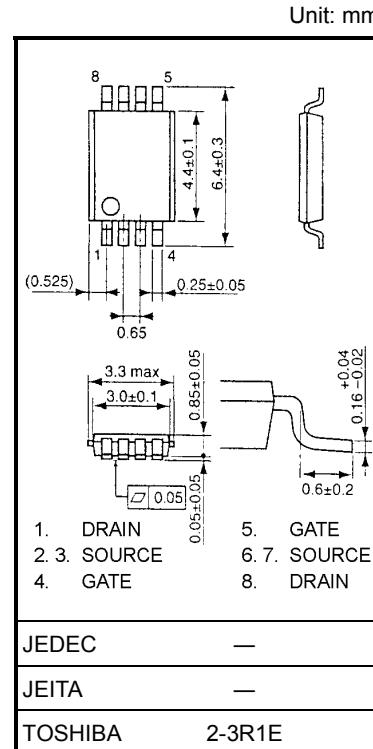
Absolute Maximum Ratings ($T_a = 25^\circ\text{C}$)

Characteristics		Symbol	Rating	Unit
Drain-source voltage		V_{DSS}	20	V
Drain-gate voltage ($R_{GS} = 20 \text{ k}\Omega$)		V_{DGR}	20	V
Gate-source voltage		V_{GSS}	± 12	V
Drain current	DC (Note 1)	I_D	6	A
	Pulse (Note 1)	I_{DP}	24	
Drain power dissipation ($t = 10 \text{ s}$) (Note 2a)	Single-device operation (Note 3a)	$P_D(1)$	1.1	W
	Single-device value at dual operation (Note 3b)	$P_D(2)$	0.75	
Drain power dissipation ($t = 10 \text{ s}$) (Note 2b)	Single-device operation (Note 3a)	$P_D(1)$	0.6	
	Single-device value at dual operation (Note 3b)	$P_D(2)$	0.35	
Single pulse avalanche energy (Note 4)		E_{AS}	46.8	mJ
Avalanche current		I_{AR}	6	A
Repetitive avalanche energy Single-device value at dual operation (Note 2a, 3b, 5)		E_{AR}	0.075	mJ
Channel temperature		T_{ch}	150	°C
Storage temperature range		T_{stg}	-55~150	°C

Note: (Note 1), (Note 2), (Note 3), (Note 4) and (Note 5): See the next page.

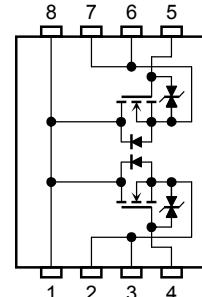
Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc.).

This transistor is an electrostatic-sensitive device. Please handle with caution.



Weight: 0.035 g (typ.)

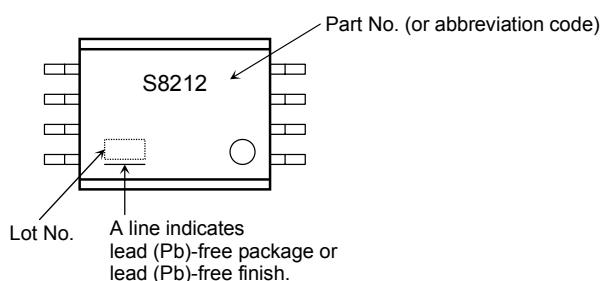
Circuit Configuration



Thermal Characteristics

Characteristics		Symbol	Max	Unit
Thermal resistance, channel to ambient (t = 10 s) (Note 2a)	Single-device operation (Note 3a)	R_{th} (ch-a) (1)	114	°C/W
	Single-device value at dual operation (Note 3b)	R_{th} (ch-a) (2)	167	
Thermal resistance, channel to ambient (t = 10 s) (Note 2b)	Single-device operation (Note 3a)	R_{th} (ch-a) (1)	208	°C/W
	Single-device value at dual operation (Note 3b)	R_{th} (ch-a) (2)	357	

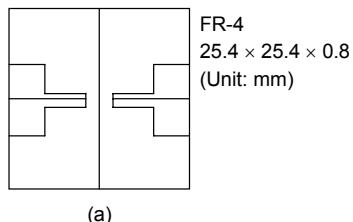
Marking (Note 6)



Note 1: Ensure that the channel temperature does not exceed 150°C.

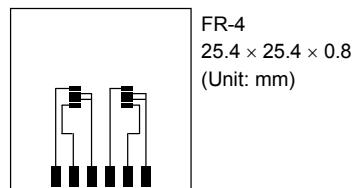
Note 2:

a) Device mounted on a glass-epoxy board (a)



(a)

b) Device mounted on a glass-epoxy board (b)



(b)

Note 3:

a) The power dissipation and thermal resistance values are shown for a single device

(During single-device operation, power is only applied to one device.).

b) The power dissipation and thermal resistance values are shown for a single device

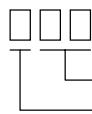
(During dual operation, power is evenly applied to both devices.).

Note 4: $V_{DD} = 16$ V, $T_{ch} = 25^\circ\text{C}$ (initial), $L = 1.0$ mH, $R_G = 25 \Omega$, $I_{AR} = 6$ A

Note 5: Repetitive rating; pulse width limited by maximum channel temperature

Note 6: ○ on lower right of the marking indicates Pin 1.

※ Weekly code: (Three digits)



Week of manufacture

(01 for the first week of a year: sequential number up to 52 or 53)

Year of manufacture

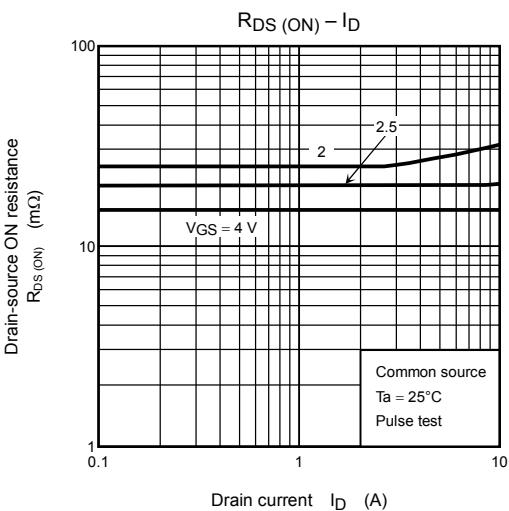
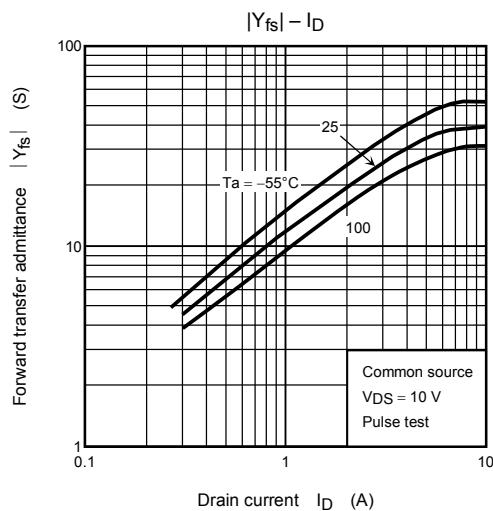
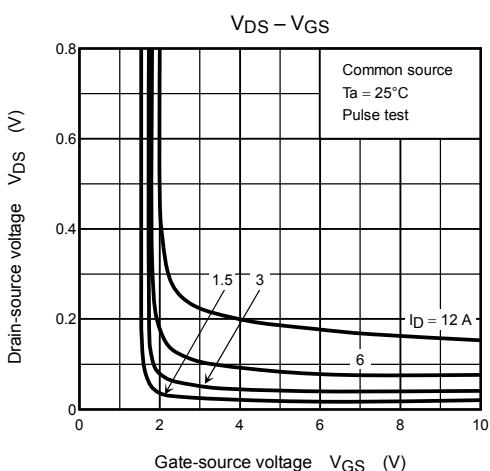
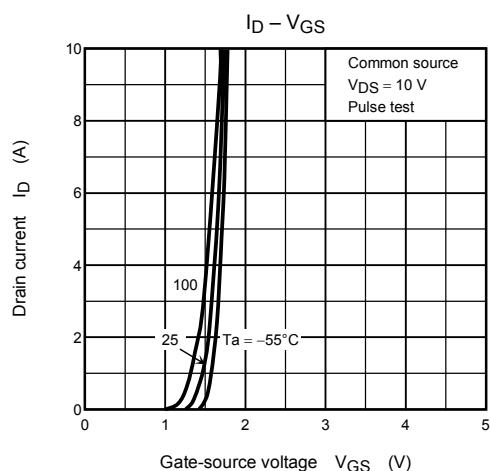
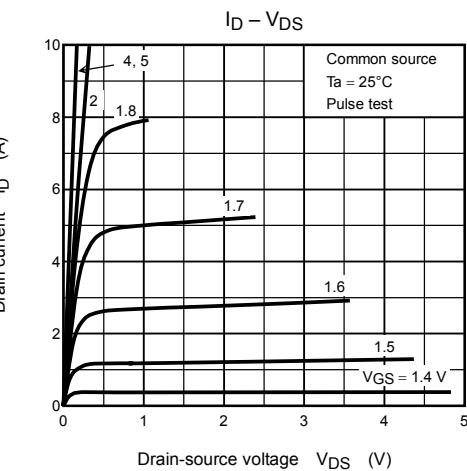
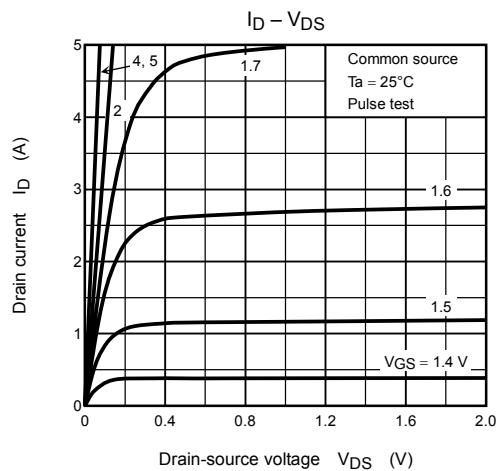
(The last digit of a year)

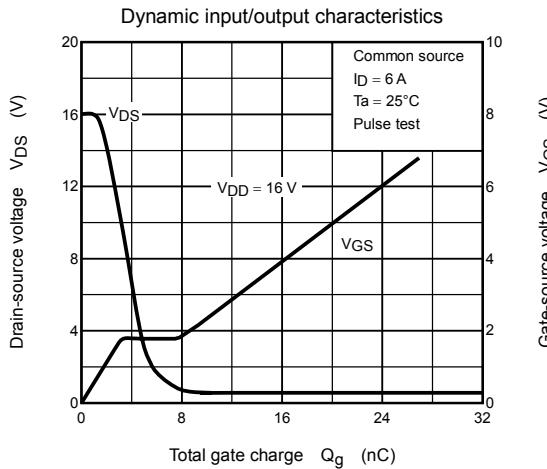
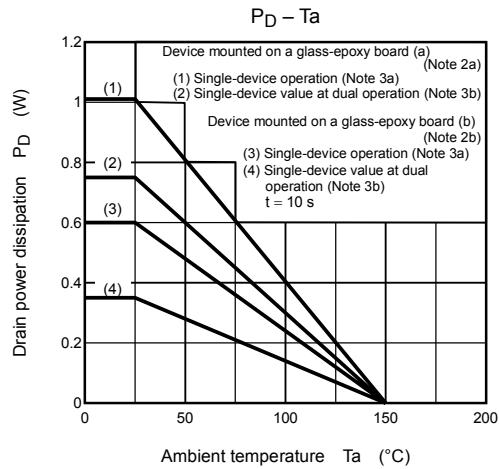
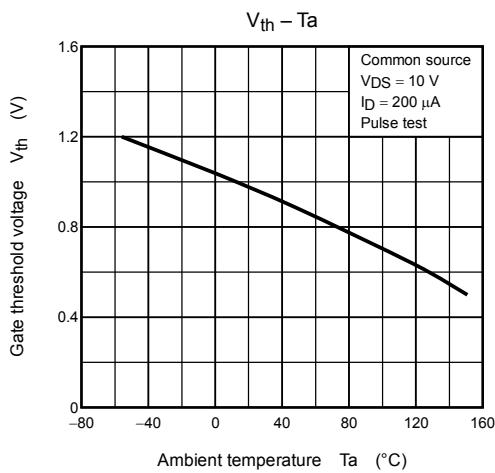
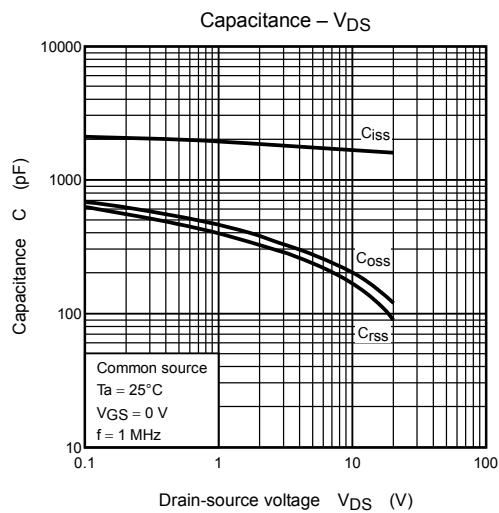
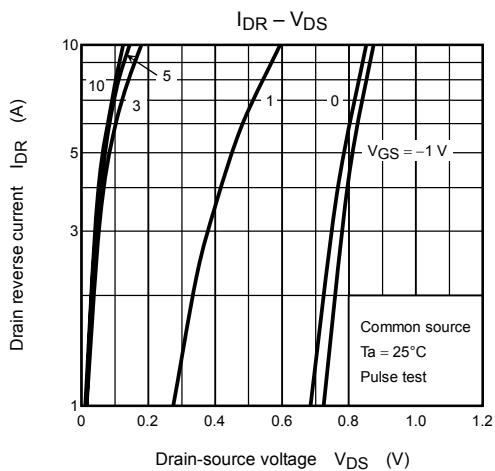
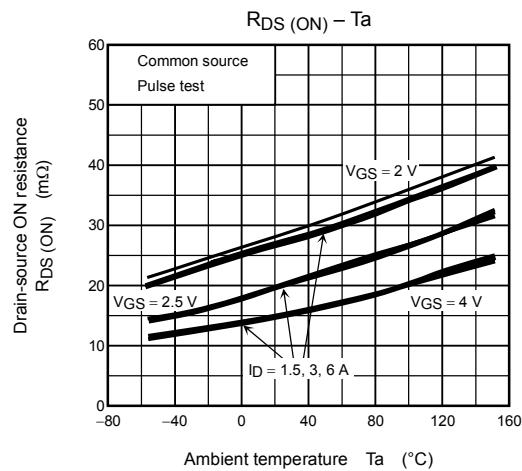
Electrical Characteristics ($T_a = 25^\circ\text{C}$)

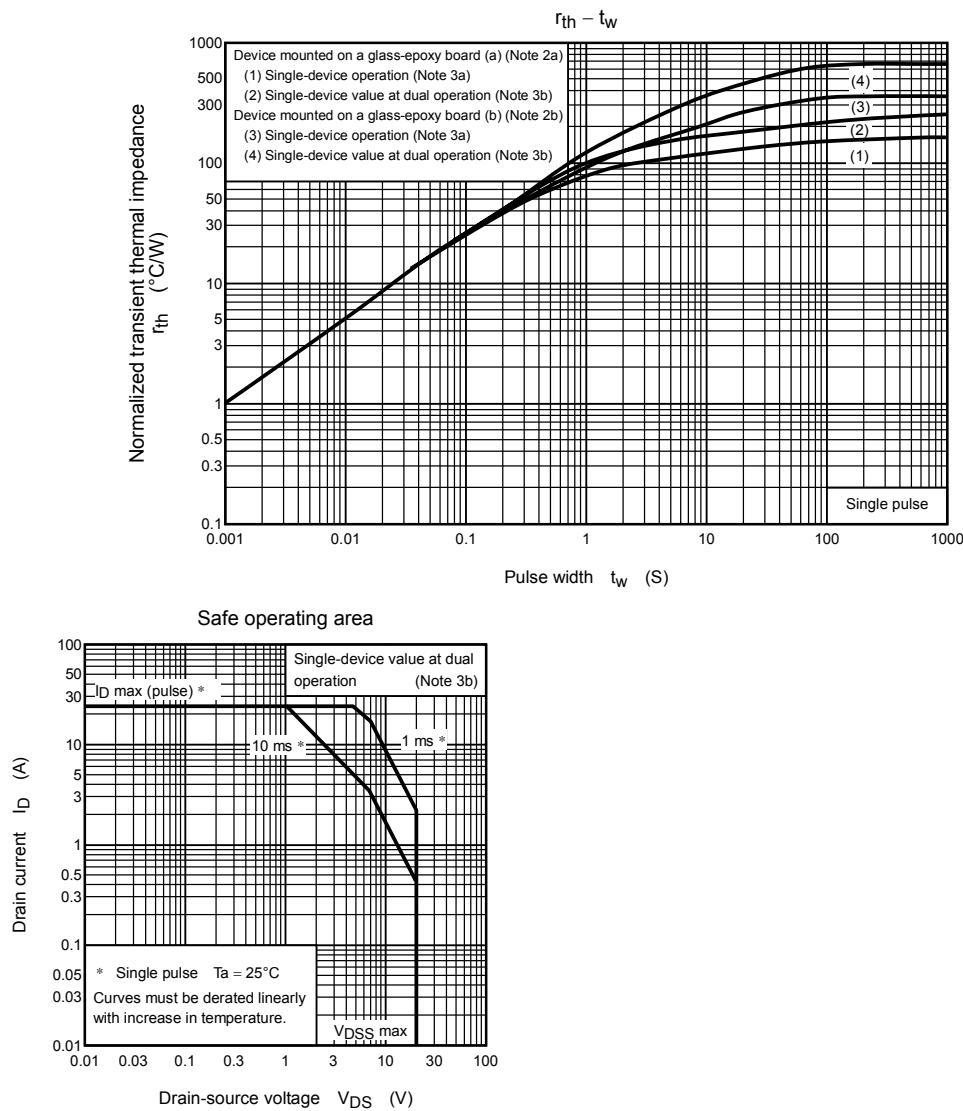
Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Gate leakage current	I_{GSS}	$V_{GS} = \pm 10\text{ V}, V_{DS} = 0\text{ V}$	—	—	± 10	μA
Drain cut-OFF current	I_{DSS}	$V_{DS} = 20\text{ V}, V_{GS} = 0\text{ V}$	—	—	10	μA
Drain-source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	$I_D = 10\text{ mA}, V_{GS} = 0\text{ V}$	20	—	—	V
	$V_{(\text{BR})\text{DSX}}$	$I_D = 10\text{ mA}, V_{GS} = -12\text{ V}$	8	—	—	
Gate threshold voltage	V_{th}	$V_{DS} = 10\text{ V}, I_D = 200\text{ }\mu\text{A}$	0.5	—	1.2	V
Drain-source ON resistance	$R_{DS(\text{ON})}$	$V_{GS} = 2.0\text{ V}, I_D = 4.2\text{ A}$	—	26	45	$\text{m}\Omega$
		$V_{GS} = 2.5\text{ V}, I_D = 4.2\text{ A}$	—	21	29	
		$V_{GS} = 4.0\text{ V}, I_D = 4.8\text{ A}$	—	16	24	
Forward transfer admittance	$ Y_{fs} $	$V_{DS} = 10\text{ V}, I_D = 3.0\text{ A}$	5.5	11	—	S
Input capacitance	C_{iss}	$V_{DS} = 10\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$	—	1590	—	pF
Reverse transfer capacitance	C_{rss}		—	180	—	
Output capacitance	C_{oss}		—	200	—	
Switching time	Rise time	t_r	 V_{GS} 5 V 0 V $I_D = 3\text{ A}$ V_{OUT} $V_{DD} \approx 10\text{ V}$ Duty $\leq 1\%$, $t_w = 10\text{ }\mu\text{s}$	—	6.4	—
	Turn-ON time	t_{on}		—	22	—
	Fall time	t_f		—	10	—
	Turn-OFF time	t_{off}		—	42	—
Total gate charge (gate-source plus gate-drain)	Q_g	$V_{DD} \approx 16\text{ V}, V_{GS} = 5\text{ V}, I_D = 6\text{ A}$	—	20	—	nC
Gate-source charge 1	Q_{gs1}		—	3.5	—	
Gate-drain ("miller") charge	Q_{gd}		—	4.5	—	

Source-Drain Ratings and Characteristics ($T_a = 25^\circ\text{C}$)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Drain reverse current	I_{DRP}	—	—	—	24	A
Forward voltage (diode)	V_{DSF}	$I_{DR} = 6\text{ A}, V_{GS} = 0\text{ V}$	—	—	-1.2	V







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- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



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